

Product Change Notification PCN98002A

Qualification of SPIL of Taiwan as an alternate Assembly Subcontractor.

Subject: Qualification of SPIL (Siliconware Precision Industries Company, Ltd.) of Taiwan as an alternate Assembly Subcontractor

Products Affected: BGA (Ball Grid Arrays)

Change Description: The addition of SPIL in Taiwan as a Qualified Assembly Facility for BGA packages. SPIL is now qualified to assemble BGAs for Xilinx. SPIL qualification for the assembly of PQ and TQ packages was previously announced under [PCN98002](#).

Product Change: There are no changes in electrical or mechanical specifications. The package piece parts (mold compounds, leadframes, etc.) as well as the manufacturing processes are totally compatible with the BGA product lines that Xilinx currently supplies.

Reason For Change: To provide additional assembly capability for BGA products. This change is part of our continuous effort towards improving total customer satisfaction.

Qualification Data: Xilinx has performed an on-site audit of this facility to verify SPIL's conformance to Xilinx and ISO 9002 quality system requirements. (SPIL has ISO 9002 certification). Reliability Qualification Testing of BGA and other packages was also performed. Summary [qualification test data](#) for the BGA package is attached. SPIL passed all Xilinx requirements to be qualified for assembly manufacturing.

Traceability: For traceability purposes, the back (bottom) side marking will show a "D" prefix on the assembly lot code.

Response: No response to this notification is required. Requests for additional data or support should be made within 90 days of notification. Please address any questions you may have via email at "pcn@xilinx.com", or directly by fax at 408 559 1368.